

STARPOWER

SEMICONDUCTOR

MOSFET

MD170HFN100L1S

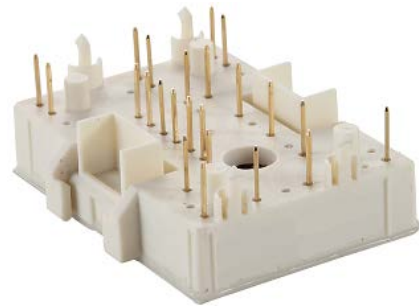
100V/170A 2 in one-package

General Description

STARPOWER MOSFET Power Module provides very low $R_{DS(on)}$ as well as optimized intrinsic diode. It's designed for the applications such SMPS and DC drives.

Features

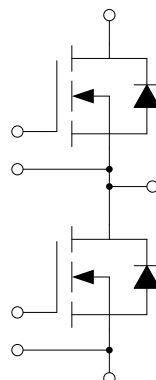
- Low $R_{DS(on)}$
- Optimized intrinsic reverse diode
- Low inductance case avoid oscillations
- Kelvin source terminals for easy drive
- Isolated heatsink using DBC technology



Typical Applications

- Main and auxiliary AC drives of electric vehicles
- DC servo and robot drives
- Battery vehicles
- UPS equipment
- Plasma cutting

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted**MOSFET**

Symbol	Description	Value	Unit
V_{DSS}	Drain-Source Voltage	100	V
V_{GSS}	Gate-Source Voltage	± 30	V
I_D	Drain Current	170	A
I_{DM}	Pulsed Drain Current	340	A
P_D	Maximum Power Dissipation @ $T_j=175^\circ\text{C}$	407	W

Inverse Diode

Symbol	Description	Value	Unit
I_S	Source Current	170	A
I_{SM}	Pulsed Source Current	340	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^\circ\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V

MOSFET Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	Static Drain-Source On-Resistance	$I_D=100\text{A}, V_{GS}=10\text{V}, T_j=25^\circ\text{C}$			9.00	m Ω
$V_{GS(th)}$	Gate-Source Threshold Voltage	$I_D=0.25\text{mA}, V_{DS}=V_{GS}, T_j=25^\circ\text{C}$	3.0		5.0	V
g_{fs}	Forward Transconductance	$V_{DS}=50\text{V}, I_D=100\text{A}$	52			S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=V_{DSS}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			75	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=V_{GSS}, V_{DS}=0\text{V}, T_j=25^\circ\text{C}$			100	nA
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1.0\text{MHz}$		6.79		nF
C_{oss}	Output Capacitance			2.47		nF
C_{rss}	Reverse Transfer Capacitance			0.99		nF
Q_g	Total Gate Charge			260		nC
Q_{gs}	Gate-Source Charge	$I_D=100\text{A}, V_{DS}=80\text{V}, V_{GS}=10\text{V}$		49		nC
Q_{gd}	Gate-Drain ("Miller") Charge			160		nC
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=50\text{V}, I_D=100\text{A}, R_G=1.03\Omega, V_{GS}=10\text{V}, T_j=25^\circ\text{C}$		24		ns
t_r	Rise Time			270		ns
$t_{d(off)}$	Turn-Off Delay Time			45		ns
t_f	Fall Time			140		ns

Inverse Diode Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode Forward Voltage	$I_S=100\text{A}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$			1.30	V
t_{rr}	Diode Reverse Recovery Time	$V_R=50\text{V}, I_F=100\text{A}, -di/dt=100\text{A}/\mu\text{s}, T_j=25^\circ\text{C}, V_{GS}=0\text{V}$			220	ns
Q_r	Diode Reverse Recovery Charge			1.64		μC

Module Characteristics $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		17		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		0.18		m Ω
R_{thJC}	Junction-to-Case (per Mosfet)		0.335	0.368	K/W
R_{thCH}	Case-to-Heatsink (per Mosfet)		0.060		K/W
	Case-to-Heatsink (per Module)		0.030		
F	Mounting Force Per Clamp	40		80	N
G	Weight of Module		36		g

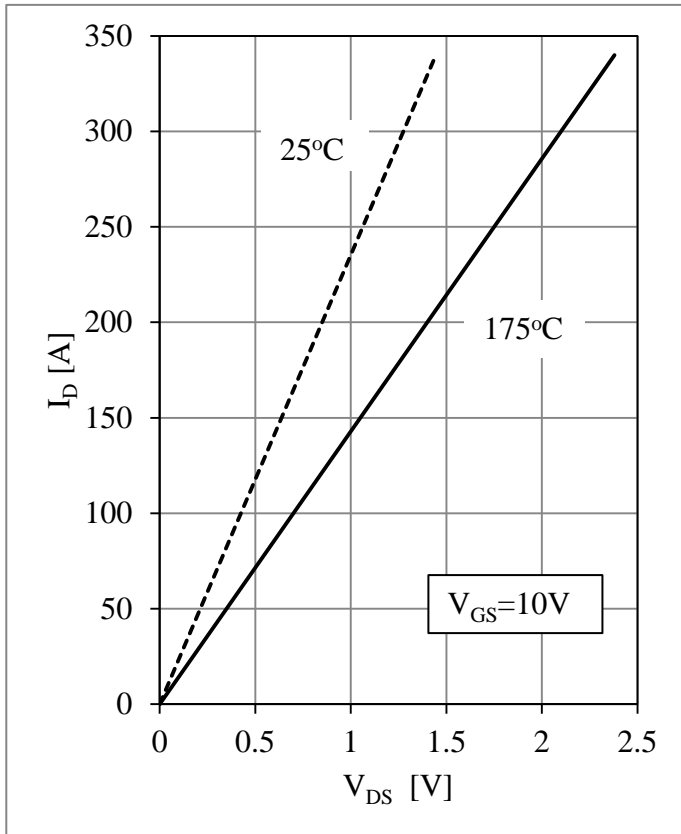


Fig 1. Mosfet Output Characteristics

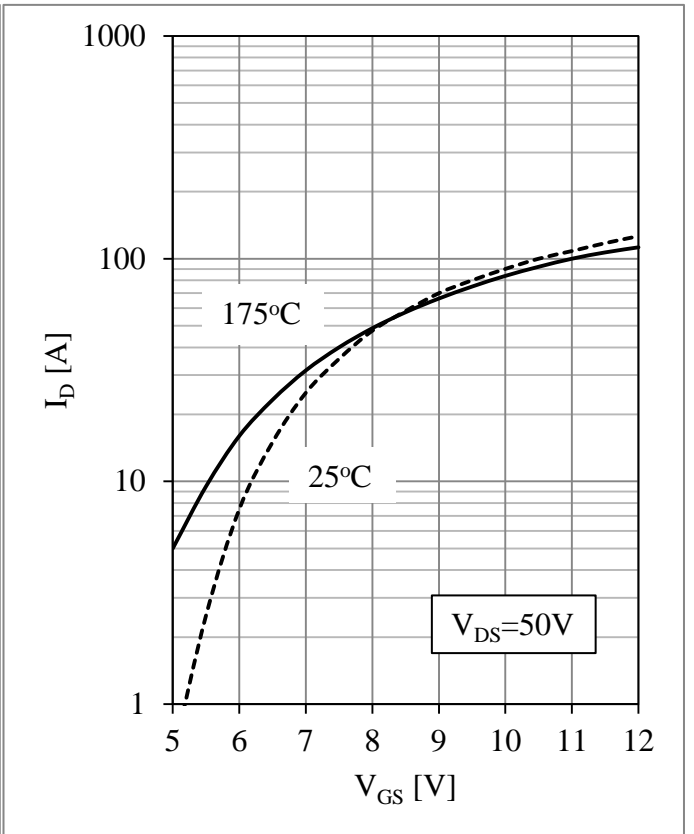


Fig 2. Mosfet Transfer Characteristics

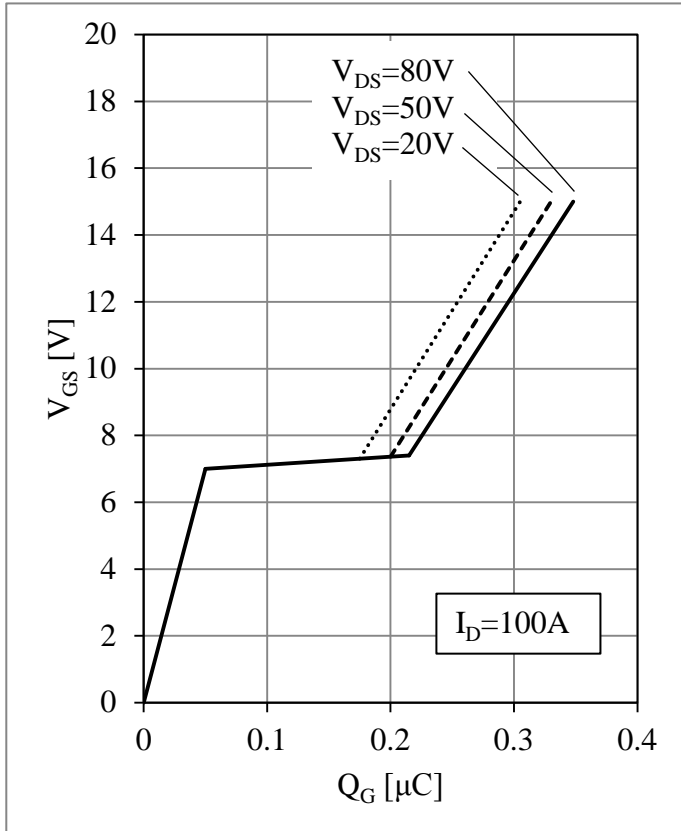


Fig 3. Gate Charge Characteristic

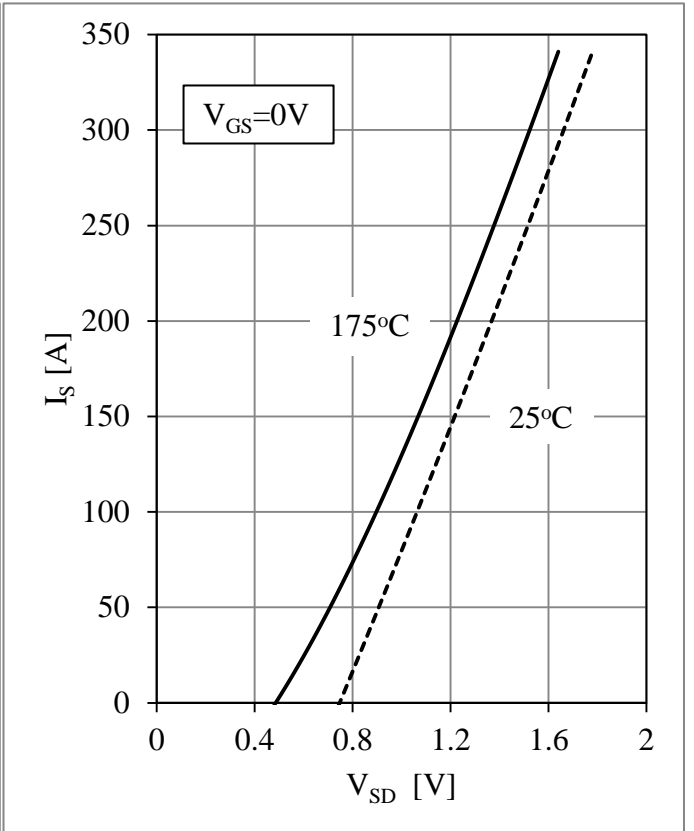


Fig 4. Inverse Diode Output Characteristics

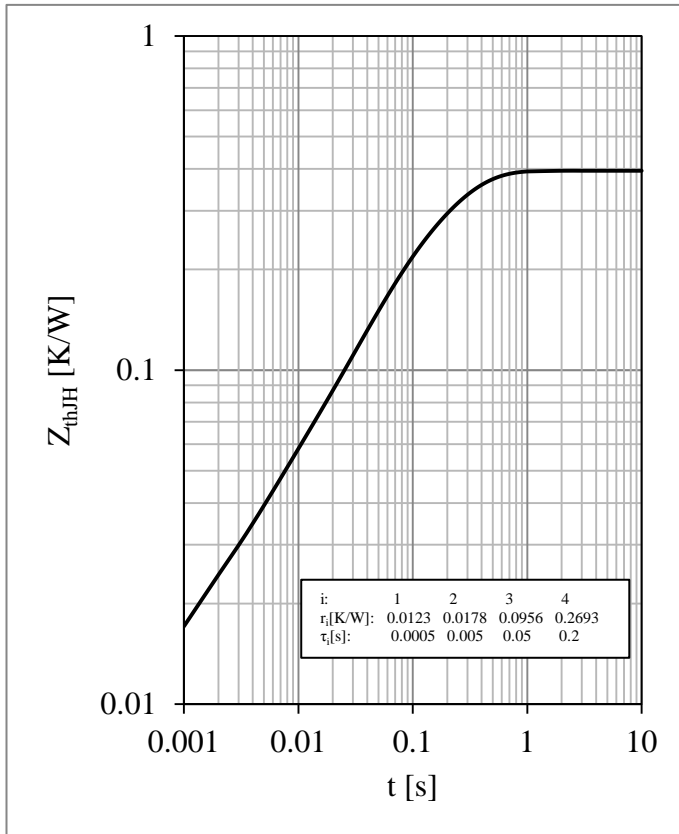
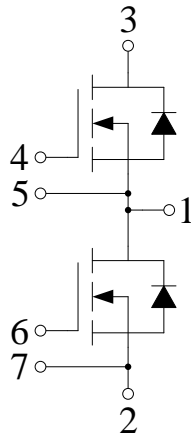


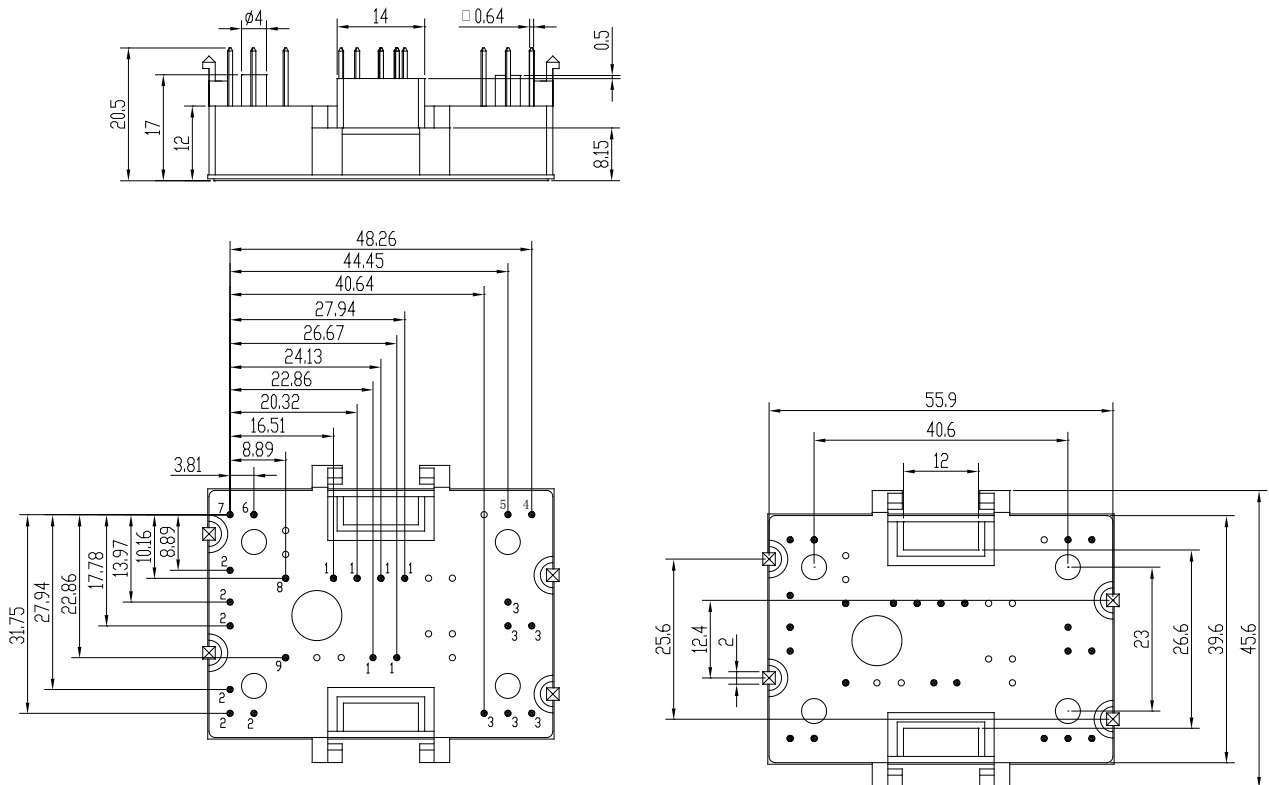
Fig 5. Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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